



Material Content Data Sheet



Sales Product Name				BSC070N10NS3 G		Issued		19. January 2018	
MA#				MA001617516					
Package				PG-TDSON-8-39		Weight*		118.80 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.666	3.09	3.09	30861	30861	
leadframe	non noble metal	iron	7439-89-6	0.049	0.04		414		
	inorganic material	phosphorus	7723-14-0	0.015	0.01		124		
	non noble metal	copper	7440-50-8	49.082	41.33	41.38	413138	413679	
wire	non noble metal	copper	7440-50-8	0.061	0.05	0.05	514	514	
encapsulation	organic material	carbon black	1333-86-4	0.076	0.06		638		
	plastics	epoxy resin	-	5.992	5.04		50436		
	inorganic material	silicondioxide	60676-86-0	31.856	26.81	31.91	268141	319215	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12219	12219	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1393	1393	
solder	noble metal	silver	7440-22-4	0.076	0.06		639		
	non noble metal	tin	7440-31-5	0.061	0.05		511		
	non noble metal	lead	7439-92-1	2.899	2.44	2.55	24405	25555	
heatspreader	non noble metal	copper	7440-50-8	0.000	0.00		1		
	non noble metal	iron	7439-89-6	0.000	0.00		1		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.00	1	0	
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		188		
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56		
	noble metal	silver	7440-22-4	1.032	0.87		8683		
	non noble metal	copper	7440-50-8	22.292	18.76	19.66	187637	196564	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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